RGS60NL65DHRBTL

650V 30A Field Stop Trench IGBT

Datasheet

V _{CES}	650V
I _C	30A
V _{CE(sat) (Typ.)}	1.65V
P_{D}	228W

Outline LPDL (TO-263L) (1) (3)

Features

- 1) Qualified to AEC-Q101
- 2) Low Collector Emitter Saturation Voltage
- 3) Short Circuit Withstand Time 8µs
- 4) Built in Very Fast & Soft Recovery FRD
- 5) Pb free Lead Plating; RoHS Compliant

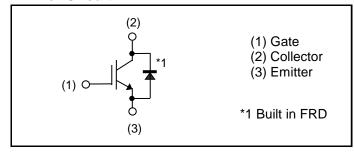
Application

General Inverter

for Automotive and Industrial Use

Heater for Automotive

Inner Circuit



Packaging Specifications

Type	Packaging	Taping
	Reel Size (mm)	330
	Tape Width (mm)	24
	Basic Ordering Unit (pcs)	1,000
	Packing Code	TL
	Marking	RGS60NL65D

● Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V _{CES}	650	V
Gate - Emitter Voltage		V_{GES}	±30	V
Collector Current	T _C = 25°C	I _C	59	А
Collector Current	T _C = 100°C	I _C	40	А
Pulsed Collector Current		I _{CP} *1	90	А
Diode Forward Current	T _C = 25°C	I _F	43	Α
	T _C = 100°C	I _F	25	А
Diode Pulsed Forward Current		I _{FP} *1	90	А
Power Dissipation	T _C = 25°C	P _D	228	W
Power Dissipation	T _C = 100°C	P _D	119	W
Operating Junction Temperature		T _j	-40 to +175	°C
Storage Temperature		T _{stg}	-55 to +175	°C

^{*1} Pulse width limited by T_{imax.}

●Thermal Resistance

Parameter	Cymbol	Values			Unit
raiailietei	Symbol	Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	-	0.63	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	-	1.55	°C/W

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
raiailletei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Collector - Emitter Breakdown Voltage	BV _{CES}	$I_{C} = 10 \mu A, V_{GE} = 0 V$	650	-	-	V
		$V_{CE} = 650V, V_{GE} = 0V,$				
Collector Cut - off Current	I _{CES}	$T_j = 25^{\circ}C$	-	-	10	μΑ
		Tj = 175°C	-	0.1	-	mA
Gate - Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30V$, $V_{CE} = 0V$	-	-	±200	nA
Gate - Emitter Threshold Voltage	$V_{GE(th)}$	$V_{CE} = 5V, I_{C} = 1.5mA$	5.0	6.0	7.0	V
		$I_C = 30A, V_{GE} = 15V,$				
Collector - Emitter Saturation Voltage	V _{CE(sat)}	$T_j = 25^{\circ}C$	-	1.65	2.10	V
		T _j = 175°C	-	2.15	-	V

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	0	Conditions		l locit		
	Symbol		Min.	Тур.	Max.	Unit
Input Capacitance	C _{ies}	$V_{CE} = 30V$,	-	980	-	
Output Capacitance	C _{oes}	$V_{GE} = 0V$,	-	80	-	pF
Reverse transfer Capacitance	C _{res}	f = 1MHz	-	13	-	
Total Gate Charge	Q_g	V _{CE} = 400V,	-	36	-	
Gate - Emitter Charge	Q_ge	$I_{\rm C} = 30A$,	-	10	-	nC
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	15	-	
Turn - on Delay Time	t _{d(on)}		-	31	-	
Rise Time	t _r	$I_C = 30A, V_{CC} = 400V,$ $V_{GE} = 15V, R_G = 10\Omega,$	-	13	-	20
Turn - off Delay Time	$t_{d(off)}$	$T_i = 25^{\circ}C$	-	94	-	ns
Fall Time	t _f	Inductive Load	-	91	-	
Turn - on Switching Loss	E _{on}	*E _{on} include diode reverse recovery	-	0.65	-	mJ
Turn - off Switching Loss	E_{off}	•	-	0.79	-	
Turn - on Delay Time	$t_{d(on)}$	$I_C = 30A$, $V_{CC} = 400V$, $V_{GE} = 15V$, $R_G = 10\Omega$, $T_i = 175$ °C	-	31	-	ns
Rise Time	t _r		-	15	-	
Turn - off Delay Time	$t_{d(off)}$		-	111	-	
Fall Time	t _f	Inductive Load	-	138	-	
Turn - on Switching Loss	E _{on}	*E _{on} include diode reverse recovery	-	0.73	-	ml
Turn - off Switching Loss	E_{off}	•	-	1.03	-	mJ
Reverse Bias Safe Operating Area	RBSOA	$I_C = 90A$, $V_{CC} = 520V$, $V_P = 650V$, $V_{GE} = 15V$, $R_G = 50\Omega$, $T_j = 175^{\circ}C$	FULL SQUARE		-	
Short Circuit Withstand Time	t _{sc}	$V_{CC} \le 360V$, $V_{GE} = 15V$, $T_j = 25^{\circ}C$	8	-	-	μs
Short Circuit Withstand Time	t _{sc} *2	$V_{CC} \le 360V$, $V_{GE} = 15V$, $T_j = 150$ °C	6	-	-	μs

*2 Design assurance without measurement

•FRD Electrical Characteristics (at $T_j = 25$ °C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
Parameter			Min.	Тур.	Max.	Offic
		I _F = 25A,				
Diode Forward Voltage	V_{F}	$T_j = 25^{\circ}C$	-	1.5	1.95	V
		T _j = 175°C	-	1.6	-	
Diode Reverse Recovery Time	t _{rr}	$I_F = 25A$, $V_{CC} = 400V$, $di_F/dt = 200A/\mu s$, $T_j = 25^{\circ}C$	-	95	1	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	6.9	ı	А
Diode Reverse Recovery Charge	Q _{rr}		-	0.37	ı	μC
Diode Reverse Recovery Energy	E _{rr}		-	16	ı	μJ
Diode Reverse Recovery Time	t _{rr}	$I_F = 25A$, $V_{CC} = 400V$, $di_F/dt = 200A/\mu s$, $T_j = 175^{\circ}C$	ı	127	ı	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	8.3	ı	А
Diode Reverse Recovery Charge	Q _{rr}		-	0.64	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	34	-	μJ

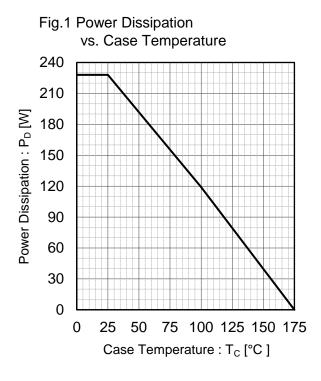


Fig.2 Collector Current vs. Case Temperature 70 60 Collector Current : I_C [A] 50 40 30 20 10 $T_i \leq 175^{\circ}C$ 0 25 50 75 100 125 150 175 0 Case Temperature : T_C [°C]

Fig.3 Forward Bias Safe Operating Area

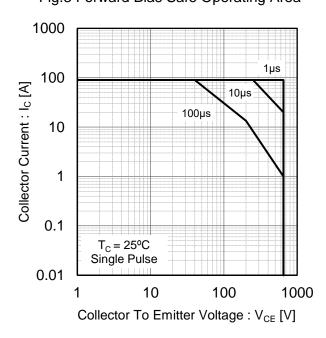


Fig.4 Reverse Bias Safe Operating Area

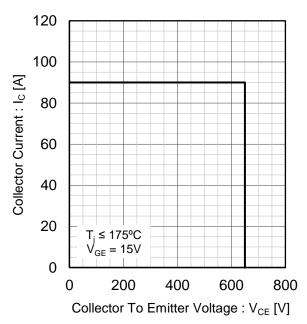


Fig.5 Typical Output Characteristics

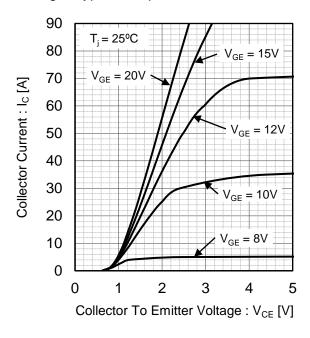


Fig.6 Typical Output Characteristics

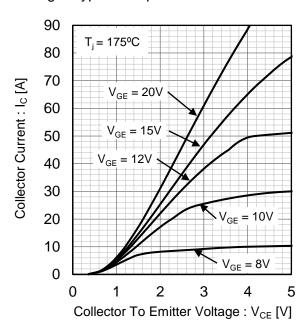


Fig.7 Typical Transfer Characteristics

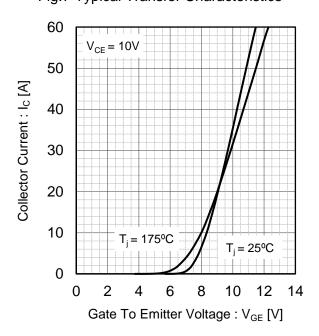


Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature

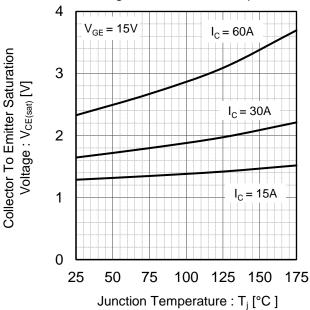


Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

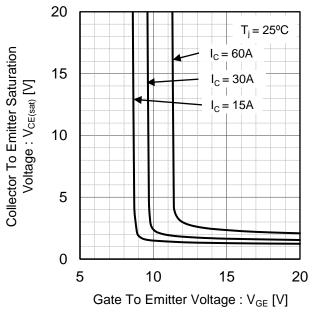


Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

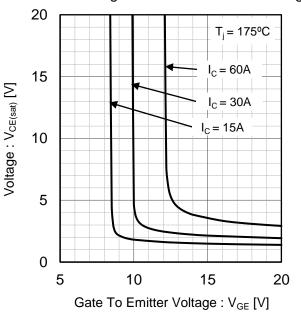


Fig.11 Typical Capacitance vs. Collector To Emitter Voltage

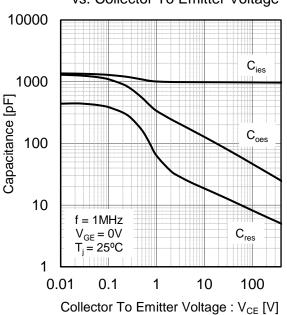
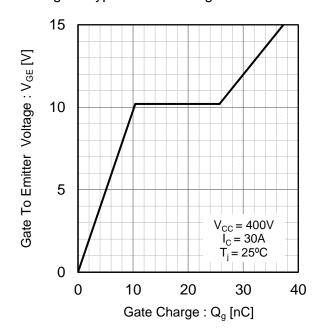
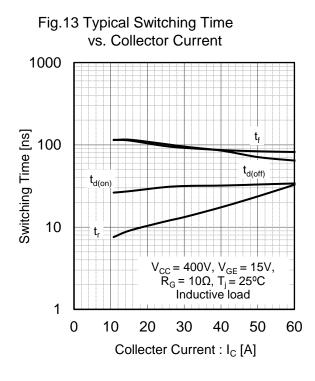


Fig.12 Typical Gate Charge



Collector To Emitter Saturation



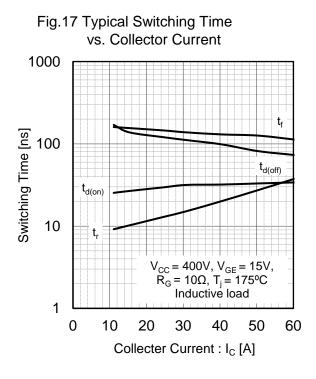
vs. Gate Resistance 1000 $t_{d(off)}$ Switching Time [ns] 100 $t_{d(on)}$ 10 $I_{C} = 400 \text{V}, V_{GE} = 15 \text{V},$ $I_{C} = 30 \text{A}, T_{j} = 25 ^{\circ} \text{C}$ Inductive load 1 0 10 20 30 40 50 Gate Resistance : R_q [Ω]

Fig.14 Typical Switching Time

Fig.15 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] 1 $\mathsf{E}_{\mathsf{off}}$ 0.1 Eor $V_{CC} = 400V, V_{GE} = 15V,$ $R_{G} = 10\Omega, T_{j} = 25^{\circ}C$ Inductive load 0.01 0 10 20 30 40 50 60 Collecter Current : I_C [A]

vs. Gate Resistance 10 Switching Energy Losses [mJ] E_{on} 1 $\mathsf{E}_{\mathsf{off}}$ 0.1 $V_{CC} = 400V, V_{GE} = 15V,$ $I_{C} = 30A, T_{j} = 25^{\circ}C$ Inductivé load 0.01 0 10 20 30 40 50 Gate Resistance : $R_G[\Omega]$

Fig.16 Typocal Switching Energy Losses



vs. Gate Resistance 1000 Switching Time [ns] 100 $t_{d(off)}$ 10 $I_{CC} = 400 \text{V}, V_{GE} = 15 \text{V},$ $I_{C} = 30 \text{A}, T_{j} = 175 ^{\circ}\text{C}$ Inductive load 1 0 10 20 30 40 50 Gate Resistance : R_q [Ω]

Fig.18 Typical Switching Time

Fig.19 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] 1 Eon 0.1 $V_{CC} = 400V, V_{GE} = 15V,$ $R_G = 10\Omega, T_j = 175^{\circ}C$ Inductivé load 0.01 0 10 20 30 40 50 60 Collecter Current : I_C [A]

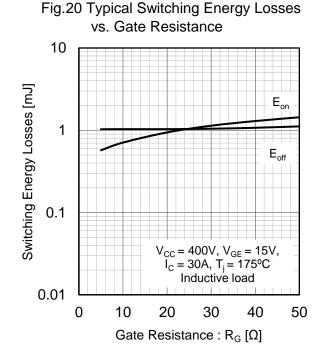


Fig.21 Typical Diode Forward Current vs. Forward Voltage

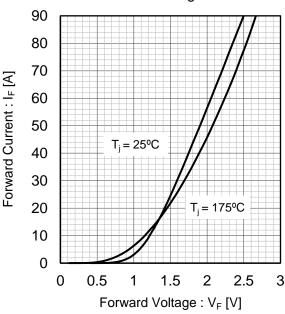


Fig.22 Typical Diode Revese Recovery Time vs. Forward Current

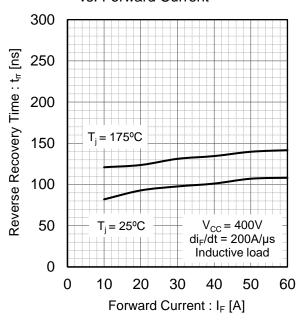


Fig.23 Typical Diode Reverse Recovery Current vs. Forward Current

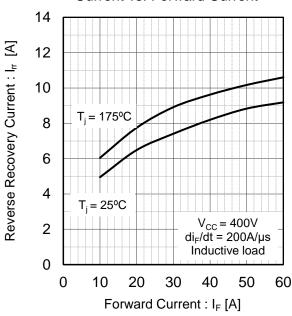


Fig.24 Typical Diode Rrverse Recovery Charge vs. Forward Current

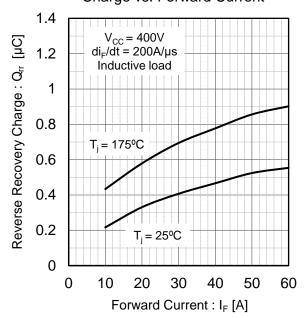


Fig.25 Typical IGBT Transient Thermal Impedance

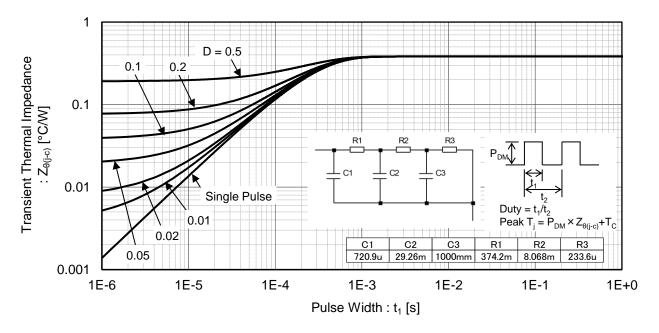
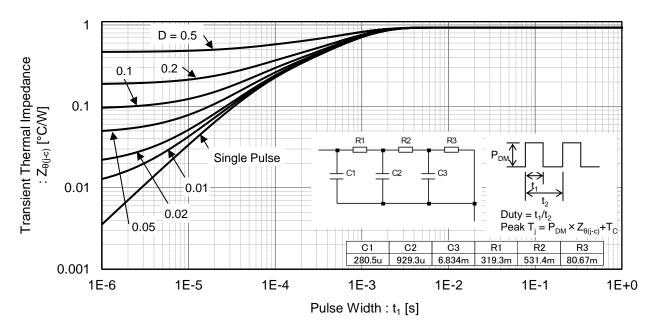


Fig.26 Typical Diode Transient Thermal Impedance



Inductive Load Switching Circuit and Waveform

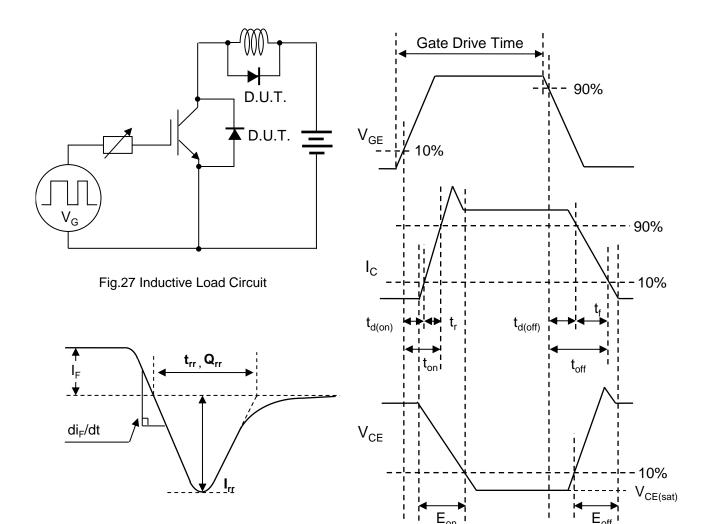


Fig.29 Diode Reverse Recovery Waveform

Fig.28 Inductive Load Waveform

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